

DB201 THRU DB207

Glass Passivated Bridge Rectifiers

Features

- Glass passivated chip
- High surge forward current capability
- Reliable low cost construction utilizing molded plastic technique
- Lead tin plated copper
- •Meet UL flammability classification 94V-0

Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any
- Note: Products with logo
 - are made by HY Electronic (Cayman) Limited.

Applications

 General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.

Maximum Ratings and Electrical Characteristics

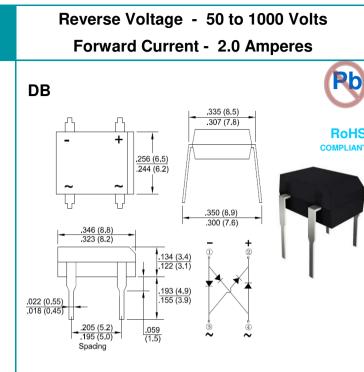
Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristics	Symbol	DB201	DB202	DB203	DB204	DB205	DB206	DB207	Unit
Maximum Repetitive Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @Ta=40 $^\circ\!$	l(AV)	2.0							А
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	IFSM	60							A
I ² t Rating for Fusing (t<8.3mS)	l ² t	14.9						A ² s	
Peak Forward Voltage per Diode at 2.0A DC	VF	1.1							V
Maximum DC Reverse Current at Rated @TJ=25°C	IR	10							μA
DC Blocking Voltage per Diode @Tj=125 $^\circ\!\!\mathrm{C}$	IN	500							
Typical Junction Capacitance (Note1)	CJ	25						pF	
Typical Thermal Resistance Junction to Ambient (Note2)	Reja	40						°C/W	
Operating Junction Temperature Range	TJ	-55 to +150							°C
Storage Temperature Range	Тѕтс	-55 to +150							°C

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

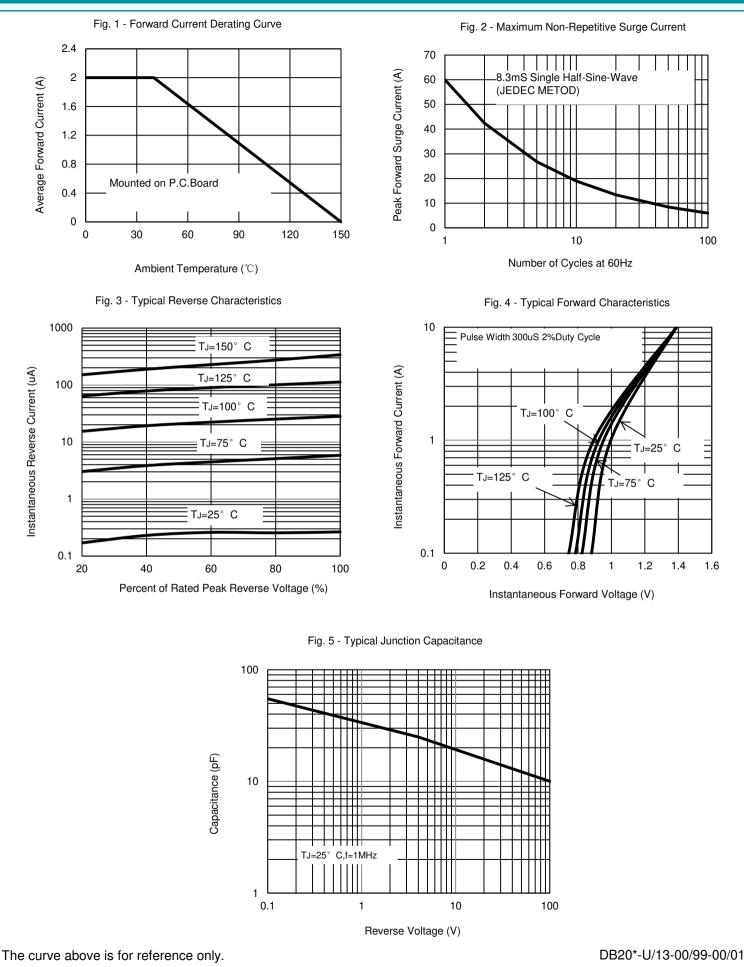
2. Thermal resistance from junction to ambient mounted on P.C.B ,with 0.5*0.5"(13*13mm) copper pads.

3. The typical data above is for reference only .



Package Outline Dimensions in Inches (Millimeters)

Rating and Characteristic Curves DB201 THRU DB207



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ALL specifications and data are subject to be changed without notice to improve reliability function or design or other reasons.

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